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PATENT Attorney Docket No. ASC-049C1 (120237/156689)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT:

Fitzgerald

SERIAL NO.:

10/774,890

GROUP NO.:

2818

FILING DATE:

February 9, 2004

EXAMINER:

Tran, Mai Huong C.

TITLE:

RELAXED SIGE PLATFORM FOR HIGH SPEED CMOS ELECTRONICS AND HIGH SPEED ANALOG CIRCUITS

Mail Stop RCE Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Sir:

In accordance with the provisions of 37 C.F.R. 1.97 and 1.98, Applicant hereby makes of record the patents and publications listed on the accompanying Form PTO-1449, and other information contained herein, for consideration by the Examiner in connection with the examination of the above-identified patent application. In accordance with the U.S. Patent Office's partial waiver of the requirement under 37 C.F.R. 1.98(a)(2)(i), only copies of the non-patent publications are enclosed.

REMARKS

In accordance with the provisions of 37 C.F.R. 1.97, this statement is being filed (CHECK ONE):

| (1) | within three (3) months of the filing date of a national application other than a continued prosecution application under 37 C.F.R. 1.53(d), or within three (3) months of the date of entry of the national stage as set forth in 37 C.F.R. 1.491 in an international application, or before the mailing of the first Office action on the merits, or before the mailing of a first Office action after the filing of a request for continued examination under 37 C.F.R. 1.114; or |
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| (2) | after the period defined in (1) but before the mailing date of a final action or a notice of allowance under 37 C.F.R. 1.311, and |
| | the requisite Statement is below, OR |
| | the requisite fee under 37 C.F.R. 1.17(p), namely \$180.00, is included herein, or |

Supplemental Information Disclosure Statement Serial No. 10/774,890 Page 2 of 2 after the mailing date of a final action or notice of allowance but before the (3) payment of the issue fee, AND the requisite Statement is below, AND . 🔲 the requisite petition fee under 37 C.F.R. 1.17(p), namely \$180.00 is included It is respectfully requested that each of the patents and publications listed on the attached Form PTO-1449, and other information contained herein, be made of record in this application. Respectfully submitted, Attorney for Applicant Goodwin Procter LLP Exchange Place Tel. No.: (617) 570-1806

Boston, Massachusetts 02109

Fax No.: (617) 523-1231

EXAMINER

FORM PTO - 1449 ATTORNEY DOCKET NO.: ASC-049C1 INFOMATION DISCLOSURE STATEMENT APPLICANT: Fitzgerald **SERIAL NO.:** 10/774,890 FEB 1 7 2006 A TAMPE FILING DATE: February 9, 2004 GROUP: 2818 U.S. PATENT DOCUMENTS NAME **CLASS SUB** FILING DATE IF EXAM. **DOCUMENT** DATE **CLASS** APPROPRIATE INIT. **NUMBER** A191 5,091,767 02/25/1992 Bean et al. 11/05/1996 Krishna et al. A192 5,571,373 05/27/1997 Brigham et al. A193 5,633,202 A194 5,710,450 01/20/1998 Chau et al. 5,976,939 11/02/1999 Thompson et al. A195 6,876,053 04/05/2005 Ma et al. A196 OTHER ART, JOURNAL ARTICLES, ETC. OTHER DOCUMENTS: (Including Author, Title, Date, Relevant Pages, Place of Publication) EXAM. INIT. Abstreiter et al., "Silicon/Germanium Strained Layer Superlattices," Journal of Crystal Growth, C135 95:431-438 (1989). Auberton-Hervé et al., "SMART-CUT®: The Basic Fabrication Process for UNIBOND® SO1 C136 Wafers," IEICE Transactions on Electronics, E80-C(3):358-363 (1997). Cao et al., "0.18-µm Fully-Depleted Silicon-on -Insulator MOSFET's," IEEE Electron Device C137 Letters, 18(6):251-253 (1997). Chau et al., "Advanced CMOS Transistors in the Nanotechnology Era for High-Performance, C138 Low-Power Logic Applications", pp. 26-30 (2004). Eichinger et al., "Characterization of MBE Growth SiGe Superlattices with SIMS and RBS, C139 Proceedings of the First International Symposium on Silicon Molecular Beam Epitaxy, 85(7):367-375 (1985). Fair, "Concentration Profiles of Diffused Dopants in Silicon," Impurity Doping Processes in C140 Silicon, Chapt. 7, pp. 318-442 (1981). Fair, "Quantified Conditions for Emitter-Misfit Dislocation Formation in Silicon," Journal of the C141 Electrochemical Society, 125(6):923-926 (1978). Fathy et al., "Formation of epitaxial layers of Ge on Si substrates by Ge implantation and C142 oxidation"," Appl. Phys. Lett., 51(17):1337-1339 (1987). Ghani et al., "Effect of oxygen on minority-carrier lifetime and recombination currents in C143 $Si_{1-x}Ge_x$ heterostructure devices", Appl. Phys. Lett., 58(12):1317-1319 (1991).

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